

#### EV-VNQ5E160K

#### VNQ5E160K evaluation board

Data brief - production data

#### **Features**

| Parameter                    | Symbol            | Value     | Unit              |
|------------------------------|-------------------|-----------|-------------------|
| Max transient supply voltage | V <sub>CC</sub>   | 41        | ٧                 |
| Operating voltage range      | V <sub>CC</sub>   | 4.5 to 28 | V                 |
| Max On-State resistance      | R <sub>ON</sub>   | 160       | mΩ                |
| Current limitation (typ)     | I <sub>LIMH</sub> | 10        | Α                 |
| Off-state supply current     | I <sub>S</sub>    | 2         | μA <sup>(1)</sup> |

- 1. Typical value with all loads connected.
- Simple single IC application board dedicated for VNQ5E160K-E
- Provides thermal heat-sinking for ease of use in prototyping
- Provides electrical connectivity for easy prototyping

#### Description

EV-VNQ5E160K provides you an easy way to connect ST's surface mounted VIPower<sup>®</sup> drivers into your existing prototype circuitry. This evaluation board comes pre-assembled with VNQ5E160K-E high-side driver.

The VNQ5E160K-E is a quad channel high-side driver manufactured using ST proprietary VIPower M0-5 technology and housed in PowerSSO-24 package. The VNQ5E160K-E is designed to drive automotive grounded loads, providing protection, diagnostics and easy 3 V and 5 V CMOS-compatible interface with any microcontroller.

The device integrates advanced protective functions such as load current limitation, inrush and overload active management by power limitation, overtemperature shut-off with autorestart and overvoltage active clamp. A dedicated

active low digital status pin is associated with every output channel that provides enhanced diagnostic functions including fast detection of overload and short-circuit to ground, overtemperature indication, short-circuit to  $V_{CC}$  diagnosis and ON-state and OFF-state open-load detection.

The diagnostic feedback of the whole device can be disabled by pulling the STAT\_DIS pin up, thus allowing wired-ORing with similar devices.

Figure 1. VNQ5E160K evaluation board



Table 1. Device summary

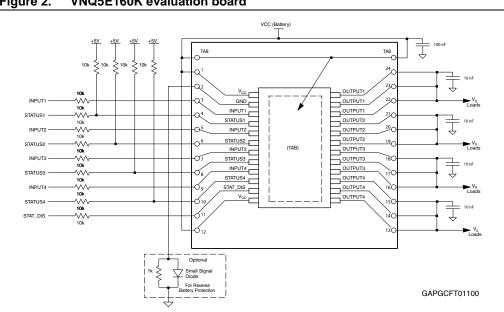
| Order code   | Reference                  |
|--------------|----------------------------|
| EV-VNQ5E160K | VNQ5E160K evaluation board |

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#### **Design recommendations** 1

This evaluation board provides mounting solution and some heat sinking capability for prototype development, but there are still external components that are required to make these devices work in any application. For further information on how the evaluation board has to be used you can refer to the AN4212 (see Appendix A: Reference documents).

Figure 2 illustrates the necessary components for any application.



VNQ5E160K evaluation board Figure 2.

ST has produced a user manual for safe designs using ST's VIPower devices. This is UM1556 (see Appendix A: Reference documents). UM1556 is a VIPower Hardware design guide that provides all necessary information to successfully design your circuit using our VIPower drivers.

All designs have different needs and requirements. Whatever design you decide to use, it will still need to be verified in order to meet your application specifications. ST implies no guarantee or warranty (see Appendix A: Reference documents).

EV-VNQ5E160K Thermal data

## 2 Thermal data

Table 2. VNQ5E160K-E thermal data

| Symbol               | Parameter                                 | Max. value | Unit |
|----------------------|---|------------|------|
| R <sub>thj-amb</sub> | Thermal resistance junction-ambient (MAX) | 30.5       | °C/W |

Table 3. PCB specifications

| Parameter               | Value       | Unit |
|-------------------------|-------------|------|
| Board dimensions        | 38 x 43     | mm   |
| Number of Cu layer      | 2           | _    |
| Layer Cu thickness      | 70          | μm   |
| Board finish thickness  | 1.6 +/- 10% | mm   |
| Board Material          | FR4         | _    |
| Thermal vias separation | 1.2         | mm   |
| Thermal vias diameter   | 0.3 /- 0.08 | mm   |

## 3 Board connector reference

Figure 3. Board layout

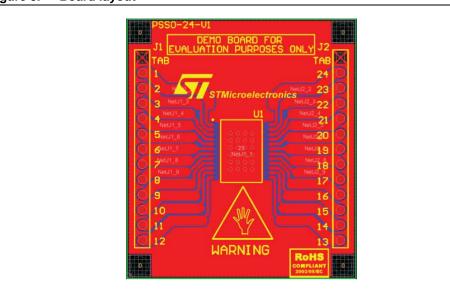


Table 4. Board connector specification

| Connector | Board lead number | Device pin function <sup>(1)</sup> |
|-----------|-------------------|------------------------------------|
| J1        | TAB               | V <sub>CC</sub>                    |
| J1        | 1                 | V <sub>CC</sub>                    |
| J1        | 2                 | GND                                |
| J1        | 3                 | INPUT1                             |
| J1        | 4                 | STATUS1                            |
| J1        | 5                 | INPUT2                             |
| J1        | 6                 | STATUS2                            |
| J1        | 7                 | INPUT3                             |
| J1        | 8                 | STATUS3                            |
| J1        | 9                 | INPUT4                             |
| J1        | 10                | STATUS4                            |
| J1        | 11                | STAT_DIS                           |
| J1        | 12                | V <sub>CC</sub>                    |
| J2        | TAB               | V <sub>CC</sub>                    |
| J2        | 13                | OUTPUT4                            |
| J2        | 14                | OUTPUT4                            |
| J2        | 15                | OUTPUT4                            |

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Table 4. Board connector specification (continued)

| Connector | Board lead number | Device pin function <sup>(1)</sup> |
|-----------|-------------------|------------------------------------|
| J2        | 16                | OUTPUT3                            |
| J2        | 17                | OUTPUT3                            |
| J2        | 18                | OUTPUT3                            |
| J2        | 19                | OUTPUT2                            |
| J2        | 20                | OUTPUT2                            |
| J2        | 21                | OUTPUT2                            |
| J2        | 22                | OUTPUT1                            |
| J2        | 23                | OUTPUT1                            |
| J2        | 24                | OUTPUT1                            |

For further clarification on pin functions please refer to the related datasheet (see Appendix A: Reference documents).

### 4 Package information

# 4.1 ECOPACK<sup>®</sup> packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>.

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EV-VNQ5E160K Reference documents

## Appendix A Reference documents

 Quad channel high side driver for automotive applications (VNQ5E160K-E, DocID 14471)

- 2. VIPower M0-5 and M0-5Enhanced high-side drivers (UM1556, DocID 023520)
- 3. PowerSSO-24 devices evaluation bord (AN4212, DocID 023983)
- 4. Evaluation Product Licence Agreement on www.st.com



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Revision history EV-VNQ5E160K

# **Revision history**

Table 5. Document revision history

| Date        | Revision | Changes          |
|-------------|----------|------------------|
| 29-Nov-2012 | 1        | Initial release. |

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